

Protecting Infotainment/Cluster Systems

We are global innovators in materials science.

Our team of engineers applies extensive industry knowledge of mechanical, thermal and electronic design to help safeguard infotainment/cluster systems from heat and EMI issues.

Infotainment electronics are employing greater functionality and higher speeds, causing more pronounced EMI and thermal challenges.

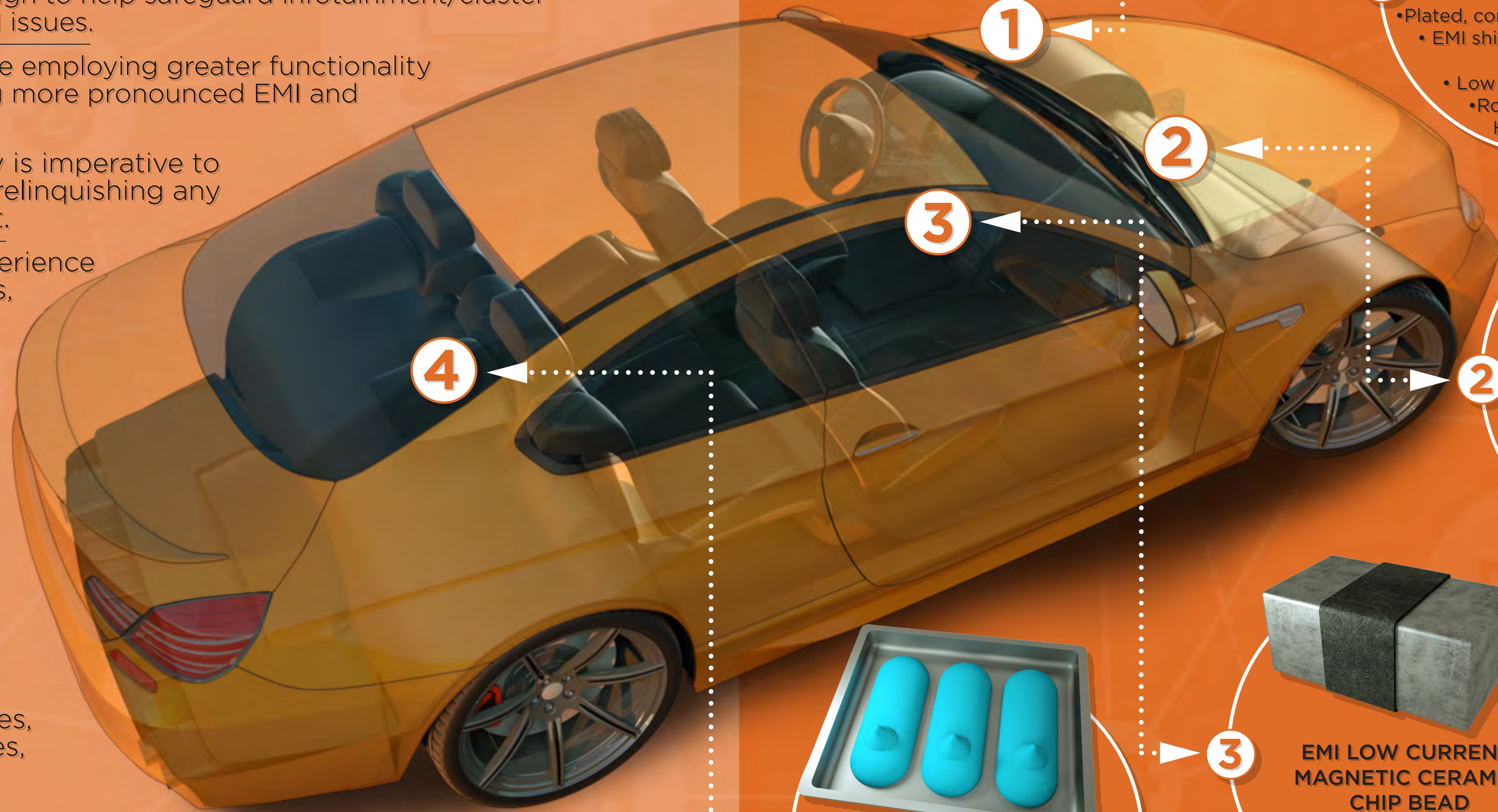
A passive cooling strategy is imperative to eliminate the fan without relinquishing any gains in the power budget.

Following 20 years of experience in infotainment electronics, Laird has a first-hand perspective on strategies that have succeeded and failed. We consult with our customers comprehensively on ridding systems of unwanted EMI and growing thermal loads, and on helping design teams succeed as they go-to-market.

We get behind the wheel to help. Laird tests, posits scenarios, models/simulates, refines working hypotheses, iterates and validates.

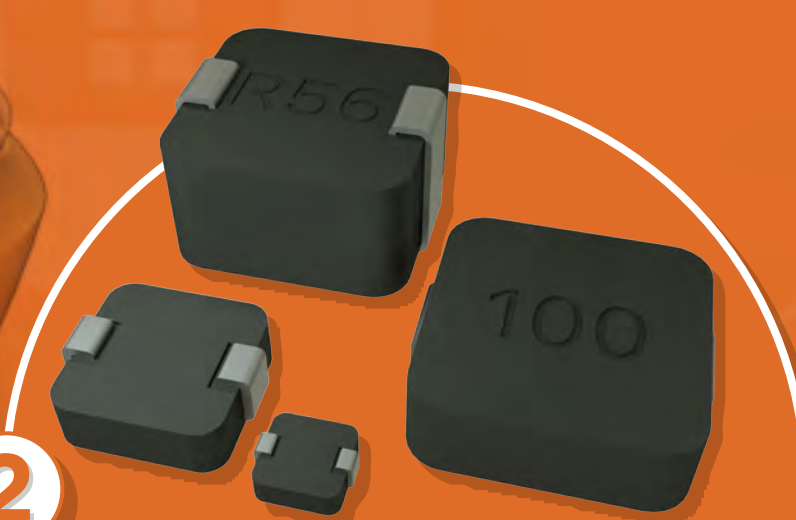
We are automotive grade. With agility for two decades.

We listen. We question. We synthesize. We know about infotainment systems. Put our experience to work.



1 FABRIC-OVER-FOAM GASKET

- Plated, conductive fabrics/foams
- EMI shielding effectiveness >100dB
- Low surface resistivity
- RoHS compliant; Halogen free



2 MGV POWER INDUCTOR

- Lowest cost design goal
- Magnetic shielded
- High current/low profile
- Low DCR/high efficiency



3 EMI LOW CURRENT MAGNETIC CERAMIC CHIP BEAD

- Superior noise suppression
- Currents up to 10A; low DCR
- Vibration resistant
- Small footprint



4 TPUTTY 607 SINGLE PART DISPENSABLE GAP FILLER

- Low stress on components
- Designs for low cost
- Maximum thermal transfer
- PCB apps





We Make Technology Work™

Protecting ADAS/Autonomous Driving Systems

Protecting LED Component Systems

TGREASE 2500

- 3.8 W/m-K thermal conductivity
- Silicone free thermal grease
- Ends migration issues
- Environmentally friendly

TPUTTY 607 ONE-PART DISPENSABLE GAP FILLER

- 6.4 W/m-K thermal conductivity
- Vertical reliability
- Low outgassing
- For PCB apps/lidar

Q-ZORB THERMOSET MICROWAVE ABSORBER

- Nomex™ or fiberglass honeycomb core
- Optimize insertion loss
- Optimize reflection loss
- For radar/radar brackets

BEAM SHADING STAMPED METAL

- Beam shading and steering
- Rapid prototyping
- Long term performance simulation
- *NAL Patent Pending

TFLEX SF800 GAP FILLER

- 8.0 W/mK conductivity
- Superior pressure vs. deflection
- Low total thermal resistance
- Excellent surface wetting

TPUTTY 508 SINGLE PART DISPENSABLE GAP FILLER

- 3.7 W/mK thermal conductivity
- Designed for automation
- Vertical stability
- Minimum component stress
- RoHS compliant

EMI LOW CURRENT MAGNETIC CERAMIC CHIP BEADS

- Superior noise suppression
- Currents up to 10A; low DCR
- Vibration resistant
- Small footprint

TGREASE 2500 THERMALLY CONDUCTIVE GREASE

- 3.8 W/mK thermal conductivity
- Environmentally friendly; silicone free
- Thoroughly wets out thermal surfaces
- No migration issues

SMD ELECTRONIC CONTACT

- Board/device interconnections
- Nickel, tin, gold, silver platings
- 0.13mm thickness

TPUTTY 508 SINGLE PART DISPENSABLE GAP FILLER

- 3.7 W/mK thermal conductivity
- Designed for automation
- Vertical stability
- Minimum component stress
- RoHS compliant

TFLEX SF600 THERMALLY CONDUCTIVE GAP PAD

- 3.0 W/mK conductivity
- Silicone-free for sensitive apps
- 0.25mm to 3.56mm thickness
- In 0.010-inch increments
- RoHS compliant

TFLEX CR200 CURE-IN-PLACE GAP FILLER

- 2.0 W/mK thermal conductivity
- 2-part silicone base
- Low viscosity
- Ideal for large gap tolerances

TFLEX 400 HD THERMAL PAD

- 40 W/mK conductivity
- High deflection gap filler
- 1mm to 4mm thicknesses
- Excellent surface wetting

FABRIC-OVER-FOAM GASKET

- Plated, conductive fabrics/foams
- EMI shielding effectiveness >100dB
- Low surface resistivity
- RoHS compliant; Halogen free

MGV POWER INDUCTOR

- Lowest cost design goal
- Magnetic shielded
- High current/low profile
- Low DCR/high efficiency

EMI LOW CURRENT MAGNETIC CERAMIC CHIP BEAD

- Superior noise suppression
- Currents up to 10A; low DCR
- Vibration resistant
- Small footprint

TPUTTY 607 SINGLE PART DISPENSABLE GAP FILLER

- Low stress on components
- Designs for low cost
- Maximum thermal transfer
- PCB apps

LOW PROFILE SMD DC-DC POWER INDUCTOR

- Lowest cost design goal
- Maximum shielding
- Down to 1.8mm part height
- For space conscious designs

BROADBAND WIRE WOUND COMMON MODE CHOKE

- Nanocrystalline core
- Enables higher switching mode designs
- High power/high efficiency apps

TFLEX CR200 CURE-IN-PLACE GAP FILLER

- 2.0 W/mK thermal conductivity
- 2-part silicone base
- Low viscosity
- Ideal for large gap tolerances



Protecting Infotainment/Cluster Systems

Protecting EV/PHEV Battery Packs

Protecting EV Powertrain Electronics

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